



Material Content Data Sheet



Sales Product Name		BFP 740ESD H6327		Issued		29. August 2013		
MA#		MA000796202						
Package		PG-SOT343-4-2		Weight*		6.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.04		393	
	non noble metal	tin	7440-31-5	0.001	0.01		101	
	inorganic material	silicon	7440-21-3	0.024	0.34	0.39	3429	3923
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		497	
	non noble metal	chromium	7440-47-3	0.010	0.15		1492	
	non noble metal	copper	7440-50-8	3.433	49.54	49.75	495338	497427
wire	noble metal	gold	7440-57-5	0.013	0.18	0.18	1830	1830
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4369	
	plastics	epoxy resin	-	0.651	9.39		93927	
	inorganic material	silicondioxide	60676-86-0	2.347	33.86	43.69	338575	436871
leadfinish	non noble metal	tin	7440-31-5	0.199	2.87	2.87	28746	28746
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31203	31203
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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